**KS-BRD01529-01: OSSAT OBC Dev board build document**

This document defines the prototype build process for this PCB assembly. It covers the process from: purchasing, through assembly and test. The reference for this document is in the footer.

**General Informaiton**

|  |  |
| --- | --- |
| **General** |  |
| This document (reference) | KS-DOC-01529-01 (also referenced in the footer) |
| Applicability | Applies to the OSSAT OBC |
| Top level part number | KS1-BRD-01467 |
| Date |  |
| Produced By |  |
| Quantity to build |  |
| Serial number(s) |  |
| Solder Type(s) |  |

**Workflow**

|  |  |  |  |  |
| --- | --- | --- | --- | --- |
| **#** | **Action** | **Info** | **Notes** | **Complete** |
| 1 | **Prints and documents** | . |  |  |
| Schematic | KS-SCH-01466-01 pdf |  |
| BOM  PCB | KS-SCH-01466-01 xlxs  KS-BRD-01467-02 (Gerber files) |  |
| Verification Document | KS-DOC-01526-02 docx |  |
| Firmware | KS-SOF-01541 |  |
| 2 | **Procurement** | . |  |  |
|  | Components |  |  |
|  | Bare Board |  |  |
|  | Stencil |  |  |
| 3 | **Kitting & Free Issue** | . |  |  |
|  | Kitting |  |  |
|  | Free Issue to sub-con |  |  |
| 4 | **Build** | **(**In house build) |  |  |
|  | Pre-Clean | Wipe with Isopropanol |  |
|  | Solder paste application | Stencil application |  |
|  | SMD Stuffing order | 1: MCU  2: SRAMS  3: Other ICs  4: Diodes and other semis  5: Resistors  6: Capacitors (small to large)  7: Other SMD |  |
|  | SMD Soldering | In-house Reflow Oven |  |
|  | PTH Stuffing & soldering | All through hole devices fitted and soldered |  |
|  | Mechanical assembly | Fit self-adhesive feet |  |
| 5 | **Cleaning** | . |  |  |
|  | Post soldering cleaning | SMD=None. Hand soldering=Isopropanol |  |
|  | **Inspection** | . |  |  |
| 6 | Confirm correct build | Part of test |  |
| 7 | **Test** | . |  |  |
|  | Functional/proving test | In-house test |  |

**Notes**

|  |
| --- |
|  |